Manual Update Sheet

SM320F2812-HT AVSSREFBG and AVDDREFBG Die Pad X-Center

ABSTRACT

This document should be used in conjuction with the *SM320F2812-HT Digital Signal Processor Data Manual* to correct two errors in the Signal Descriptions table.

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Trademarks

1 Introduction

In the Signal Descriptions table of the *SM320F2812-HT Digital Signal Processor Data Manual*, AVSSREFBG and AVDDREFBG have the wrong DIE PAD X-CENTER (µm) values. The correct values are shown in the table below.

Table 1-1. Signal Descriptions

NAME(1)	PIN NO. 172-PIN HFG	DIE PAD NO.	DIE PAD X-CENTER (µm)	DIE PAD Y-CENTER (µm)	I/O/Z(2)	PU/PD(3)	DESCRIPTION
ADC ANALOG INPUT SIGNALS							
AVSSREFBG	12	17	**1736.4**	42.6	I		ADC Analog GND
AVDDREFBG	13	18	**1831.7**	42.6	I		ADC Analog Power (3.3 V)

(1) Typical drive strength of the output buffer for all pins is 4 mA except for TDO, XCLKOUT, XF, XINTF, EMU0, and EMU1 pins, which are 8 mA.
(2) I = Input, O = Output, Z = High impedance
(3) PU = pin has internal pullup; PD = pin has internal pulldown

2 Revision History

DATE	REVISION	NOTES
November 2021	*	Initial Release

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